Product Change Notification: BLAS-24KMOI079

Date:

13-Jul-2026

Product Category:

USB Power Delivery

Notification Subject:

CCB 7286 Final Notice: Qualification of ATP7 as an additional assembly site for MCP22350-1I/Q8X, MCP22350-2I/Q8X, MCP22350T-1I/Q8X and MCP22350T-2I/Q8X catalog part numbers (CPN) available in 28L VQFN (4x4x0.9mm) package.

Affected CPNs:

BLAS-24KMOI079_Affected_CPN_07132026.pdf
BLAS-24KMOI079_Affected_CPN_07132026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for MCP22350-1I/Q8X, MCP22350-2I/Q8X, MCP22350T-1I/Q8X and MCP22350T-2I/Q8X catalog part numbers (CPN) available in 28L VQFN (4x4x0.9mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**		**Change (Yes/No)**
Assembly Site	Amkor Assembly & Test (Shanghai)	Amkor Assembly & Test (Shanghai)	Amkor Technology Philippines (P3/P4),	Yes

	Co., LTD (ANAC)	Co., LTD (ANAC)	INC. (ATP7)	
Wire Material	CuPdAu	CuPdAu	CuPdAu	No
Die Attach Material	CRM-1085A (PFAS-Free)	CRM-1085A (PFAS-Free)	CRM-1085A (PFAS-Free)	No
Molding Compound Material	G631BQF	G631BQF	G631BQF	No
Lead-Frame Material	C194	C194	C194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 10 August 2026 (date code: 2633)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	November 2024					**>**	**July 2026**					**August 2026**				
Work Week	44	45	46	47	48		27	28	29	30	31	32	33	34	35	36
Initial PCN Issue Date					X											
Qual Report Availability									X							
Final PCN Issue Date									X							
Estimated Implementation Date													X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: November 27, 2024: Issued initial notification.
July 13, 2026: Issued final notification. Attached the qualification report. Added column "Change (Yes/No)" in the pre and post change table. Updated parts list, PCN title, description of change and qual title to remove CPNs UPD350A/Q8X, UPD350A-I/Q8X, UPD350B/Q8X, UPD350B-I/Q8X, UPD350BT/Q8X, UPD350C/Q8X, UPD350C-I/Q8X, UPD350D/Q8X, UPD350D-I/Q8X, UPD350DT/Q8X and UPD350DT-I/Q8X due to being EOL'ed under PCN **CENO-08FBKS196**. Provided estimated first ship date to be on August 10, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-24KMOI079_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

MCP22350-1I/Q8X

MCP22350-2I/Q8X

MCP22350T-1I/Q8X

MCP22350T-2I/Q8X

Qualification Report Summary

RELIABILITY LABORATORY

PCN #: BLAS-24KMOI079

Date:
June 29, 2026

Qualification of ATP7 as an additional assembly site for MCP22350-1I/Q8X, MCP22350-2I/Q8X, MCP22350T-1I/Q8X and MCP22350T-2I/Q8X catalog part numbers (CPN) available in 28L VQFN (4x4x0.9mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of ATP7 as an additional assembly site for MCP22350-1I/Q8X, MCP22350-2I/Q8X, MCP22350T-1I/Q8X and MCP22350T-2I/Q8X catalog part numbers (CPN) available in 28L VQFN (4x4x0.9mm) package.

QUAL ID:	R2600125 Rev. A
MP CODE:	TAT027Q8XA0A
Part No.:	UPD350A-I/Q8X
Bonding No.:	BD-002878-01
CCB No.:	7286

Lead Frame

Paddle Size:	114x114mils
Material:	C194
DAP Surface Prep:	DR-Ag
Process:	Etched
Lead Lock:	Yes
Part Number:	101369406
Plating Composition:	Matte Sn

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	CRM-1085A
Conductive:	Yes

Mold Compound

Mold Compound:	G631BQF

Package

Type:	28L VQFN
Package Size:	4x4x0.9mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
ATP7261600004.000
ATP7261600005.000
ATP7261600008.000

Result: **Pass**

Conclusion:

Qualification of TAT02 mask / MCP22350-1I/Q8X product / CuPdAu wire in 28L VQFN 4x4x0.9mm package at MMT site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture Soak Precondition Prior to Stresses	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C Electrical Test: 25°C and 85°C System: LTX_D1X_HI_CFG	JESD22-A113, JEDEC J-STD-020	231 units each lot / 3 lots	0/231 (Electrical, each lot);	Pass	Lot IDs: R2600125-1 / ATP7261600004.000, R2600125-2 / MMT-261901090.000, R26001253 / MMT-261901091.000

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temp Storage	175°C / 504 hours Electrical Test: 25°C and 85°C System: LTX_D1X_HI_CFG	JESD22-A103	45 units / 3 lots	0/45 (each lot)	Pass	Lot IDs: R2600125-1 / ATP7261600004.000, R2600125-2 / MMT-261901090.000, R26001253 / MMT-261901091.000

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temperature Cycling	-65°C / +150°C Air to Air / 500 Cycles Electrical Test: 85°C System: LTX_D1X_HI_CFG	JESD22-A104	77 units each lot / 3 lots	0/77 Electrical (each lot); WBP: 0/5 (Lot 1 only);	Pass	Lot IDs: R2600125-1 / ATP7261600004.000, R2600125-2 / MMT-261901090.000, R26001253 / MMT-261901091.000

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 3.3V Electrical Test: 25°C and 85°C System: LTX_D1X_HI_CFG	JESD22-A110	77 units each lot / 3 lots	0/77 Electrical (each lot);	Pass	Lot IDs: R2600125-1 / ATP7261600004.000, R2600125-2 / MMT-261901090.000, R26001253 / MMT-261901091.000

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Unbiased HAST	+130°C / 85%RH / 96 hours Electrical Test: 25°C System: LTX_D1X_HI_CFG	JESD22-A118	77 units each lot / 3 lots	0/77 Electrical (each lot);	Pass	Lot IDs: R2600125-1 / ATP7261600004.000, R2600125-2 / MMT-261901090.000, R26001253 / MMT-261901091.000

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	0/22	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q100 -001	5 units / 1 lot	0/5	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Wire Sweep	15%	X-ray	15 wires each lot / 3 lots	0/45	Pass